



## **Environmental Verification Standards for Space Hardware**

**Alan R. Hoffman and Kristan E. Evans**  
*Jet Propulsion Laboratory, Pasadena, CA USA*

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### **Topics**

- **Background**
  - JPL Design Principles
  - JPL Flight Project Practices
- **Environmental Design and Verification**
- **Environmental Program Flow**
- **Environmental Verification Summary**
- **Environmental Design and Test Margins**
- **Summary**

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## JPL Environmental Testing Standards

- **Design Principles**

- Capture institutional standards for designing, verifying, validating, and operating flight systems

- **Flight Project Practices**

- Establish standards of uniformity, where standardization is judged to have significant benefit
- Capture approaches and methods important to sponsors
- Incorporate lessons learned that were key to past successes, and where deviations created significant problems
- Require management review and approval to waive

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## JPL Environmental Testing Standards (Cont.)

- **Flight Project Practices (Cont.)**

- 6.13 Design and Verification for Environmental Compatibility
  - Flight hardware designed and verified to be fully compatible with all anticipated environments.
  - System level environmental test program: modal, static, random vibration, acoustic, thermal, EMI/EMC and pyroshock
  - Assembly/subsystem level environmental test program: random vibration, acoustic, thermal pyroshock, EMC, and atmospheric

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## **JPL Environmental Testing Standards (Cont.) Flight Project Practices (Cont.)**

### **•6.13 Design and Verification for Environmental Compatibility (Cont.)**

- Test Authorization: project approved and certified**
- Test Execution: approved procedures**
  - qualification and flight acceptance testing**
  - Protoflight testing all flight articles**
  - Qualification testing one flight unit**
    - followed by flight acceptance**
    - testing all other flight units**
- Test Configuration**
  - All hardware environmentally tested before system level environmental tests**
  - System level environmental tests include full complement of flight hardware**

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## **JPL Environmental Testing Standards (Cont.) Flight Project Practices (Cont.)**

### **•6.13 Design and Verification for Environmental Compatibility (Cont.)**

- Post-Test Documentation: Test results documented including exceptions**
- Test Certification-Review of test objectives and requirements satisfied by project**

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**JPL Environmental Testing Standards (Cont.)  
Flight Project Practices (Cont.)**

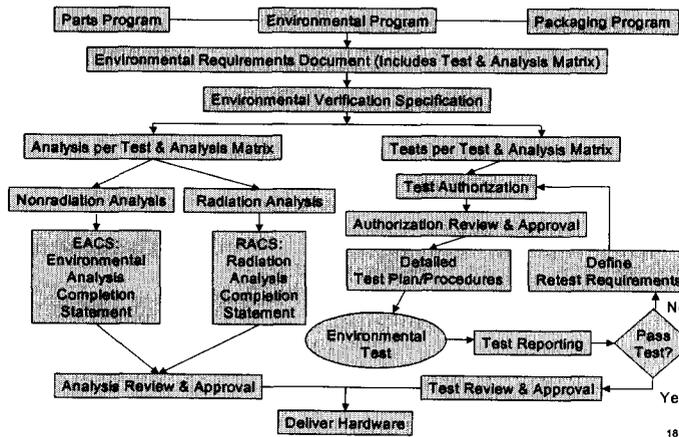
- 6.13 Design and Verification for Environmental Compatibility (Cont.)
  - Document Standards (ie implement this Flight Project Practice)
    - Spacecraft System Dynamic and Static Testing
    - System Thermal Testing
    - Assembly and Subsystem Level Environmental Verification

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*Typical Environmental Program Flow*



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### TYPICAL TEST REQUIREMENTS AND MARGINS (CONT.)

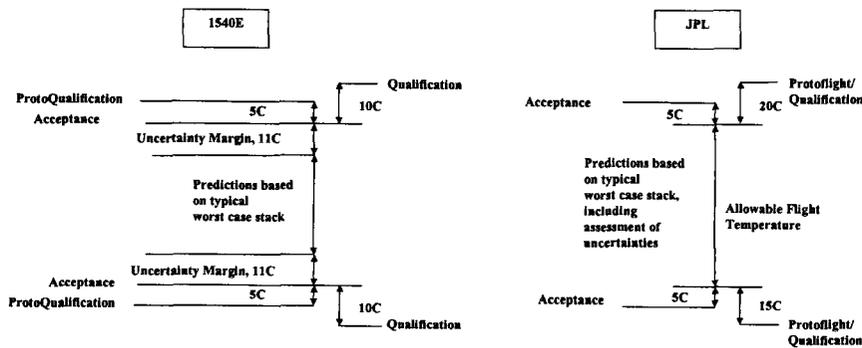
Test Description	Assembly			Spacecraft System
	Flight Acceptance	Protoflight	Qualification	Protoflight
Temperature	Allow Flt + 5°C  Cycles: 1-10 depending on mission cycles. Electronics Dwell: 60 hr. hot / 8 hr. cold Mechanisms Dwell: 24 hr. hot / 24 hr. cold	-35 to 75°C or Allow Flt +20 & -15°C  Cycles: 1-10 depending on mission cycles. Electronics Dwell: 144 hr. hot / 24 hr. cold Mechanisms Dwell: 24 hr. hot / 24 hr. cold	-35 to 75°C or Allow Flt +20 & -15°C  Cycles: 1-10 depending on mission cycles. Electronics Dwell: 144 hr. hot / 24 hr. cold Mechanisms Dwell: 24 hr. hot / 24 hr. cold	Temp. within Allowable Flt & not to exceed assembly PF.  Dwell time and Number of Thermal Cycles are Mission Dependent
Pressure Profile	None	1.5 X MAX dP/dt	1.5 X MAX dP/dt	Facility Limited
EMC RF Susceptibility Emissions	None (grounding/ isolation only)	MEFL + 6 dB Freq. Dependent Margin > 60 dB	MEFL + 6 dB Freq. Dependent Margin > 60 dB	MEFL + 6 dB Freq. Dependent Margin > 60 dB
EMC Radiated Emissions	None (grounding/ isolation only)	MEFL - 6 dB Freq. Dependent	MEFL - 6 dB Freq. Dependent	MEFL - 6 dB Freq. Dependent

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### Thermal Margins Comparisons



Besides more conservative overall margin for JPL, there is another significant difference. The JPL approach requires the assessment of uncertainties in the definition of worst-case thermal scenarios.

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## Summary

- **Environmental Design and Verification Standards for flight systems have been evolving at JPL and other NASA centers for the last 40 years.**

- **JPL documenting in institutional standards imbedded in Flight Project Practices**

- **System level environmental test program: modal, static, random vibration, acoustic, thermal, EMI/EMC and pyroshock**

- **Assembly/subsystem level environmental test program: random vibration, acoustic, thermal pyroshock, EMC, and atmospheric**

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*Backup*

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## Assure Product Reliability Hardware Terminology

TERMINOLOGY	JPL	GSFC	EUROPEAN	OTHER TERMS
Procopart		Part		component, element
			specific item name	
Subassembly		Assembly(?) pwr & gyro		component, slice, tray, unit, element, blackbox
Assembly		component, unit, section (testable level)		unit, element, blackbox, instrument
Subsystem		Subsystem, instrument, module, structural assembly	↓	unit, element, blackbox, instrument, system
System		Payload = spacecraft, laboratory, observatory, satellite	spacecraft	spacecraft, instrument, subsystem

Suggestions: s/c system - (engineering + payload)  
 instrument system - single instrument  
 payload system - group of instruments

Issue: 1) slice, tray, synonymous with subassembly  
 2) define assembly levels up-front in doc list

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